YETDA INDUSTRY LTD.

Technical Data Sheet

MODEL NO：S3535UV4P-M-405nm **3535 Package 3.45*3.45*2.0mm Chip LEDs**

Features：

- RoHS compliant
- Compatible with automatic placement equipment
- Compatible with reflow solder process

Applications：

- UV Curing, UV Printing
- Security, Banknote
- Nail Polish Curing, Mosquito Killer

Dice material	Emitted color	Lens Color
InGaN	UV	Water Clear

Electrical/Optical Characteristics(Ta=25℃)

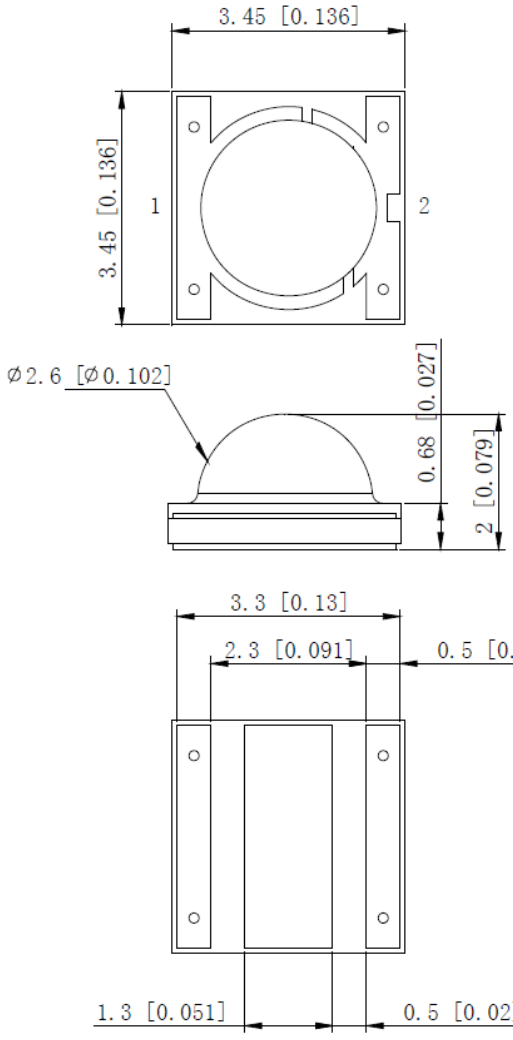
Parameter	Test Condition	Symbol	Value			Unit
			Min	Typ	Max	
Peak wavelength	IF=350mA	λp	400		410	K
Forward voltage	IF=350mA	VF	2.8	.	3.8	V
Radiation Flux	IF=350mA	Φe	500	580		mW
Radiation Flux	IF=500mA	Φe	700	800	--	mW
Viewing angle at 50% Iv	IF=350mA	2θ1/2	--	120	--	Deg
Reverse current	Vr=5V	IR	--	-	10	μA

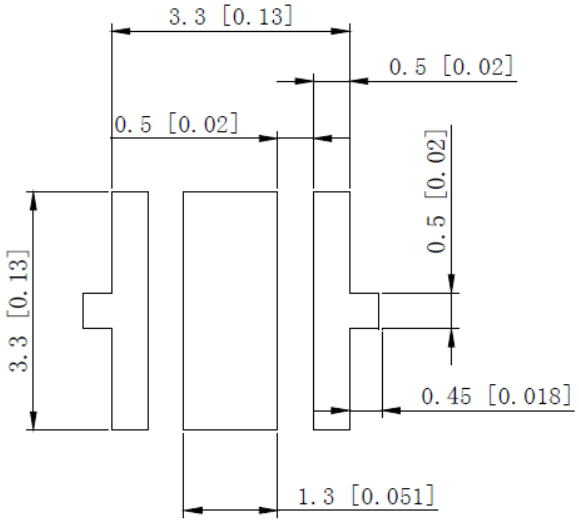
Absolute Maximum Ratings(Ta=25℃)

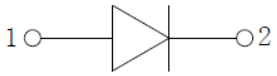
Parameter	Symbol	Value	Unit
Power dissipation	Pd	2.8	W
Forward current	IF	550	mA
Reverse voltage	VR	5	V
Operating temperature range	Top	-40 ~+85	℃
Storage temperature range	Tstg	-40 ~+85	℃
Peak pulsing current (1/8 duty f=1kHz)	IFP	700	mA

2017SEPT14Y

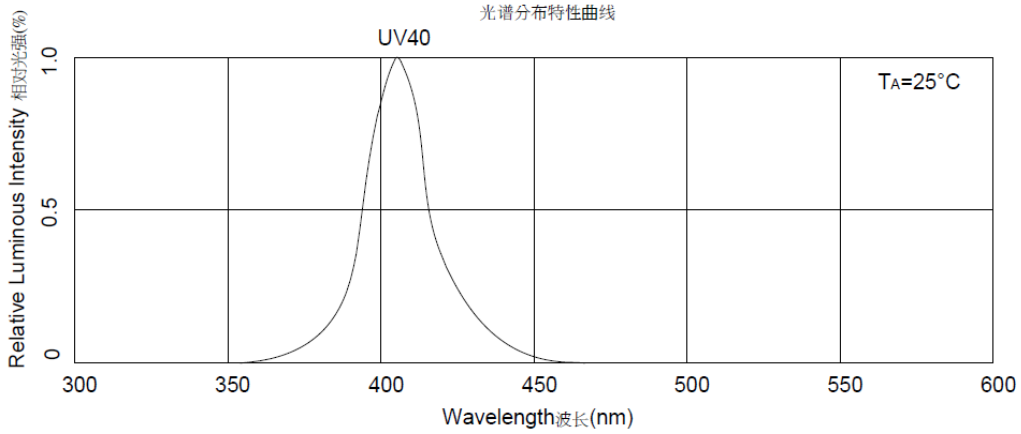
PACKAGING DIMENSIONS



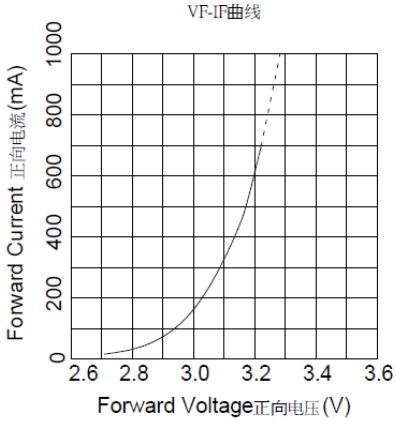




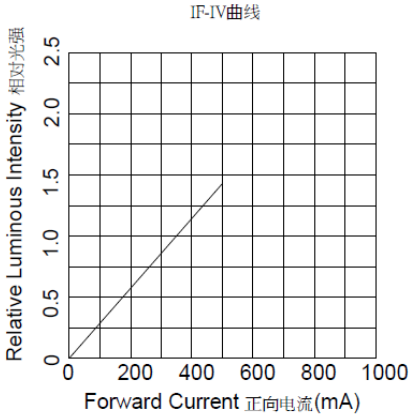
Relstive Spectral Distribution
光谱分布特性曲线



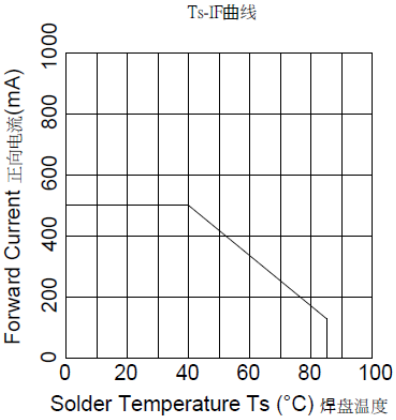
Volt-Ampere Characteristics
VF-IF曲线



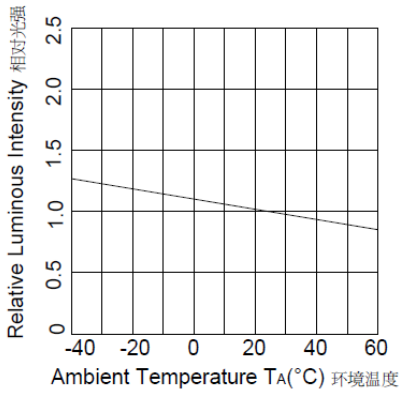
Forward Current VS. Relative Intensity
IF-IV曲线



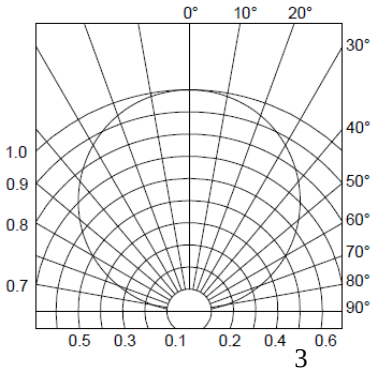
Soldering Temperature VS. Forward Current
Ts-IF曲线



Ambient Temperature VS. Relative Intensity
Ta-IV曲线



Radiation Diagram
辐射特性曲线

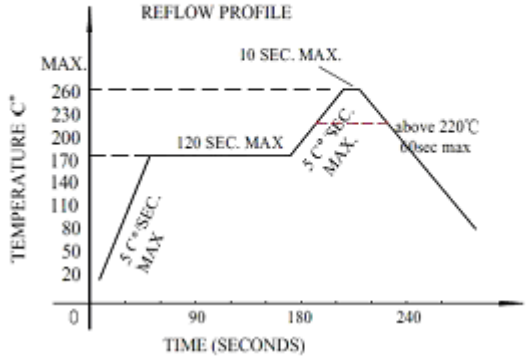


Precautions For Use：
Over－current－proof
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change （Burn out will happen）
Storage
1. The operation of temperature and R.H. are：5℃～30℃, 60％R.H. Max.
2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year（from production date）.
3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is：60℃±5℃ for 15hrs.

■ Reflow Temp/Time

■ Temperature-profile (Surface of circuit board)

Use the following conditions shown in the figure.



NOTES:

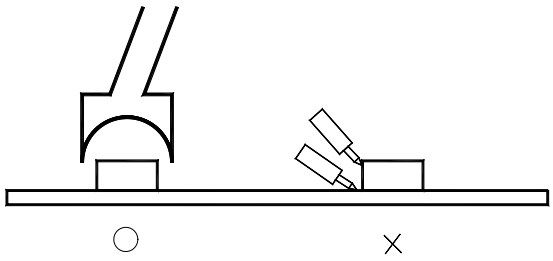
1. We recommend the reflow temperature 245℃(±5℃).the maximum soldering temperature should be limited to 260℃.
2. dont cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

■Soldering iron

Basic spec is ≤ 5sec when 260℃. If temperature is higher, time should be shorter (+10℃→ -1sec).Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 230℃ .

■Rework

1. Customer must finish rework within 5 sec under 260℃.
2. The head of iron can not touch copper foil
3. Twin-head type is preferred.



■ **Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 、solder etc.**

Dimensions of Tape (Unit: mm)